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**Alexei L. Glebov
Paul O. Leisher**
Editors

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Introduction

Optical components are crucial for laser performance and form a foundation for advances in laser science and technology. All around the globe, vast and constantly growing research efforts are dedicated to developing new and more advanced laser components and systems. Along this line, packaging solutions for optical components enable their most efficient and consistent integration in laser systems. Laser component packaging is decisive for stable and reliable laser operations while not only improving laser characteristics but also enabling broader laser usability and applications.

Cross-listed between the LASE and OPTO symposia of SPIE Photonics West, the Components and Packaging for Laser Systems conference is primarily focused on achievements and progress made in the field of optical components and packaging technology for laser systems such as semiconductor lasers, solid state lasers, fiber lasers, gas lasers, continuous-wave and pulsed lasers, ultra-short pulsed lasers, and others. Examples of optical components for lasers include macro- and micro-optic lenses and arrays, diffractive and holographic elements, coating technology, polarization optics, fiber optic connectors, couplers, splitters, and isolators, laser gain media, beam transformation systems, components for ultra-short pulsed lasers, components for coherent and spectral beam combining, mid-IR elements, novel design methodologies, and advanced manufacturing techniques. Examples of packaging technology include assembly and mounting solutions of optical components, thermal management and packaging approaches in high-power lasers, laser array packaging and lensing, novel active and passive alignment techniques, laser system reliability, and package modelling.

This conference was created to address a gap in the technical program at Photonics West. Specifically, the developers working on component and packaging technologies (especially those common to several classes of laser systems) did not have a dedicated venue where they could present to their colleagues, customers, and suppliers. Prior to the creation of this conference, such talks would either be relegated to conferences specific to one laser system class, or more commonly, not be presented at all. In this inaugural year, our strong international committee comprising engineers and scientists from academia and industry did an outstanding job of building up and promoting this new conference, as evidenced by the large number of high quality papers we received. We were also delighted to see very strong attendance of the presentations throughout the week, and before an overflow room was designated, almost all seats were filled with many standees backed up into the hallway.

In closing, we are very thankful to the committee, authors, and attendees who made this year such a great success and we are looking forward to an even better conference next year.

Alexei L. Glebov
Paul O. Leisher